



**AOS**  
**SEMICONDUCTOR**

## 产品规格说明书

Product Data Sheet

AOS1G04xx

WEB | [www.aossemi.cn](http://www.aossemi.cn) 



电源管理IC



通信接口芯片



二三极管



LDO稳压器



逻辑器件



MOSFETs



运算放大器



显示驱动



MCU单片机



光电器件



AOS1G04 Single Inverter Gate

DESCRIPTIONS

The AOS1G04 Single inverter gate is designed for 1.65V to 5.5V Vcc operation .The AOS1G04 device performs the Boolean function Y= A̅ . The CMOS device has high output drive while maintaining low static power dissipation over a broad Vcc operating range. The AOS1G04 is available in Green SOT23-5, SC70-5 and XDFN1X1-6 packages. It operates over an ambient temperature range of -40°C to 125°C.

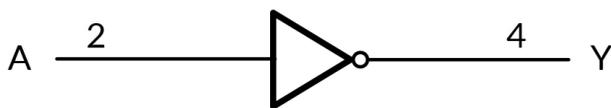
FEATURES

- Operating Voltage Range: 1.65V to 5.5V
Low Power Consumption: 1µA (Max)
Operating Temperature Range: -40°C to 125°C
Inputs Accept Voltage to 5.5V
High Output Drive: ± 24mA at Vcc=3.0V
Ioff Supports Partial -Power-Down Mode Operation
Micro Size Packages: SOT23-5, SC70-5, XDFN1X1-6

APPLICATIONS

- AC Receiver
Blu-ray Players and Home Theaters
Desktops or Notebook PCs
Digital Video Cameras (DVC)
Mobile Phones
Personal Navigation Device(GPS)
Portable Media Player

Functional Block Diagram



Device Information(1)

Table with 3 columns: PART NUMBER, PACKAGE, BODY SIZE (NOM). Rows include AOS1G04 with packages SOT23-5, SC70-5, and XDFN1X1-6.

(1)For all available packages, see the orderable addendum at the end of the data sheet.

FUNCTION TABLE

Table with 2 columns: INPUTS, OUTPUT. Rows show logic levels H and L for input A and output Y.

Y=A̅
H=High Voltage Level
L=Low Voltage Level



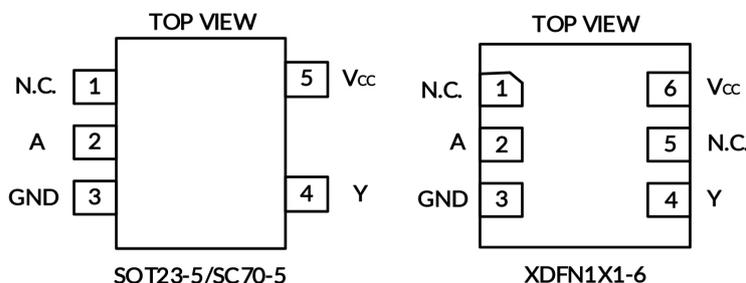
PACKAGE/ORDERING INFORMATION

PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING <sup>(1)</sup>	MSL <sup>(3)</sup>	PACKAGE OPTION
AOS1G04	AOS1G04XF5	-40°C~+125°C	SC70-5 <sup>(4)</sup>	1G04	MSL3	Tape and Reel , 3000
	AOS1G04XC5	-40°C~+125°C	SOT23-5	1G04	MSL3	Tape and Reel , 3000
	AOS1G04XUTDN6	-40°C~+125°C	XDFN1X1-6	04 <sup>(5)</sup>	MSL3	Tape and Reel , 5000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) AOS classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F, Please align with AOS if your end application is quite critical to the preconditioning setting or if you have special requirement.
- (4) Equivalent to SOT353.
- (5) 04: Identification Code.

PIN CONFIGURATIONS



PIN DESCRIPTION

PIN		NAME	I/O <sup>(1)</sup>	FUNCTION
SOT23-5/SC70-5	XDFN1X1-6			
1	1	N. C. <sup>(2)</sup>	-	Not connected
2	2	A	I	Input
3	3	GND	P	Ground
4	4	Y	O	Output
-	5	N. C. <sup>(2)</sup>	-	Not connected
5	6	V <sub>cc</sub>	P	Power pin

- (1) I=input, O=output, P=power.
- (2) There is no internal connection. Typically, GND is the recommended connection to a heat spreading plane.



## Specifications

Absolute Maximum Ratings<sup>(1)</sup>Over operating free-air temperature range (unless otherwise noted)<sup>(1)(2)</sup>

		MIN	MAX	UNIT		
V <sub>CC</sub>	Supply voltage range		-0.5	6.5	V	
V <sub>I</sub>	Input voltage range <sup>(2)</sup>		-0.5	6.5		
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>		-0.5	6.5		
V <sub>O</sub>	Voltage range applied to any output in the higher lowstate <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> ± 0.5		
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA	
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50		
I <sub>O</sub>	Continuous output current			± 50		
	Continuous current through V <sub>CC</sub> or GND			± 100		
J <sub>A</sub>	Package thermal impedance <sup>(4)</sup>		SOT23-5		230	°C/W
			SC70-5		380	
			XDFN1X1-6		438	
T <sub>J</sub>	Junction temperature <sup>(5)</sup>		-65	150	°C	
T <sub>stg</sub>	Storage temperature		-65	150		

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the Recommended Operating Conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD-51.
- (5) The maximum power dissipation is a function of T<sub>J(MAX)</sub>, R<sub>JA</sub>, and T<sub>A</sub>. The maximum allowable power dissipation at any ambient temperature is P<sub>D</sub> = (T<sub>J(MAX)</sub> - T<sub>A</sub>) / R<sub>JA</sub>. All numbers apply for packages soldered directly onto a PCB.



### ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per EIA/JESD22-a114, all pins	± 4000	V
		Charged-device model (CDM), per JS-002, all pins	± 1500	
		Machine model (MM), per EIA/JESD22-a115, all pins	± 200	



### ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.



**ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (Full=-40°C to +125°C, typical values are at T<sub>A</sub>= +25°C, unless otherwise noted.) <sup>(1)</sup>

**Recommended Operating Conditions**

PARAMETER	SYMBOL	V <sub>CC</sub>	MIN	MAX	UNIT
Supply Voltage	V <sub>CC</sub>	Operating	1.65	5.5	V
		Data retention only	1.5		
High-Level Input Voltage	V <sub>IH</sub>	V <sub>CC</sub> =1.65V to 1.95V	0.65×V <sub>CC</sub>		
		V <sub>CC</sub> =2.3V to 2.7V	1.7		
		V <sub>CC</sub> =3V to 3.6V	2		
		V <sub>CC</sub> =4.5V to 5.5V	0.7×V <sub>CC</sub>		
Low-Level Input Voltage	V <sub>IL</sub>	V <sub>CC</sub> =1.65V to 1.95V		0.35×V <sub>CC</sub>	
		V <sub>CC</sub> =2.3V to 2.7V		0.7	
		V <sub>CC</sub> =3V to 3.6V		0.8	
		V <sub>CC</sub> =4.5V to 5.5V		0.3×V <sub>CC</sub>	
Input Voltage	V <sub>I</sub>		0	5.5	
Output Voltage	V <sub>O</sub>		0	V <sub>CC</sub>	
Input Transition Rise or Fall	t <sub>r</sub> , v	V <sub>CC</sub> =1.8V±0.15V, 2.5V±0.2V		20	ns/V
		V <sub>CC</sub> =3.3V±0.3V		10	
		V <sub>CC</sub> =5V±0.5V		5	
Operating Temperature	T <sub>A</sub>		-40	125	°C

(1)All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.



DC Characteristics

PARAMETER		CONDITIONS	V <sub>CC</sub>	TEMP	MIN	TYP	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> =-100μA	1.65V to 5.5V	Full	V <sub>CC</sub> -0.1			V
		I <sub>OH</sub> =-4mA	1.65V		1.2			
		I <sub>OH</sub> =-8mA	2.3V		1.9			
		I <sub>OH</sub> =-16mA	3V		2.4			
		I <sub>OH</sub> =-24mA			2.3			
		I <sub>OH</sub> =-32mA	4.5V		3.8			
V <sub>OL</sub>		I <sub>OH</sub> =100μA	1.65V to 5.5V	Full			0.1	V
		I <sub>OH</sub> =4mA	1.65V				0.45	
		I <sub>OH</sub> =8mA	2.3V				0.3	
		I <sub>OH</sub> =16mA	3V				0.4	
		I <sub>OH</sub> =24mA					0.55	
		I <sub>OH</sub> =32mA	4.5V				0.55	
I <sub>I</sub>	A or B inputs	V <sub>I</sub> =5.5V or GND	0V to 5.5V	+25°C		±0.1	±1	μA
				Full			±5	
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> =5.5V	0	+25°C		±0.1	±1	μA
				Full			±10	
I <sub>CC</sub>		V <sub>I</sub> =5.5V or GND, I <sub>O</sub> =0	1.65V to 5.5V	+25°C		0.1	1	μA
				Full			10	
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> -0.6V, Other inputs at V <sub>CC</sub> or GND	3V to 5.5V	Full			500	μA
C <sub>i</sub> (Input Capacitance)		V <sub>I</sub> =V <sub>CC</sub> or GND	3.3V	+25°C		4		pF

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



AC Characteristics

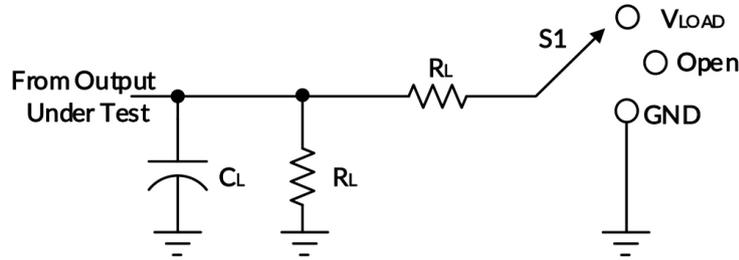
PARAMETER	SYMBOL	TEST CONDITIONS		MIN <sup>(2)</sup>	TYP <sup>(3)</sup>	MAX <sup>(2)</sup>	UNIT
Propagation Delay	t <sub>pd</sub>	V <sub>CC</sub> =1.8V ± 0.15V	C <sub>L</sub> =30pF, R <sub>L</sub> =1k		13.0		ns
		V <sub>CC</sub> =2.5V ± 0.2V	C <sub>L</sub> =30pF, R <sub>L</sub> =500		5.1		
		V <sub>CC</sub> =3.3V ± 0.3V	C <sub>L</sub> =50pF, R <sub>L</sub> =500		4.2		
		V <sub>CC</sub> =5V ± 0.5V	C <sub>L</sub> =50pF, R <sub>L</sub> =500		3.3		
Power dissipation capacitance	C <sub>pd</sub>	V <sub>CC</sub> =1.8V	f=10MHz		16		pF
		V <sub>CC</sub> =2.5V			18		
		V <sub>CC</sub> =3.3V			18		
		V <sub>CC</sub> =5V			20		

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.
- (2) This parameter is ensured by design and/or characterization and is not tested in production.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



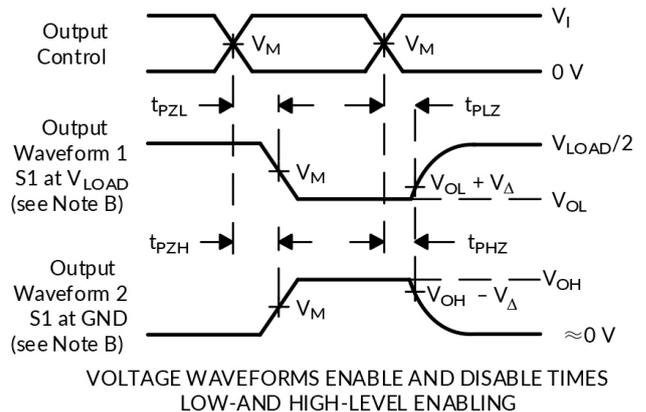
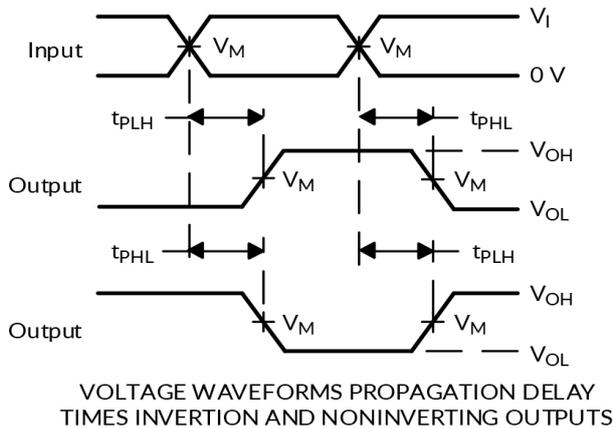
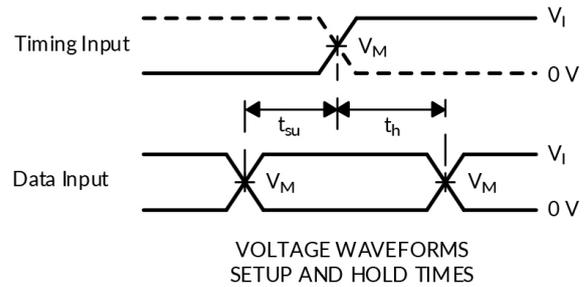
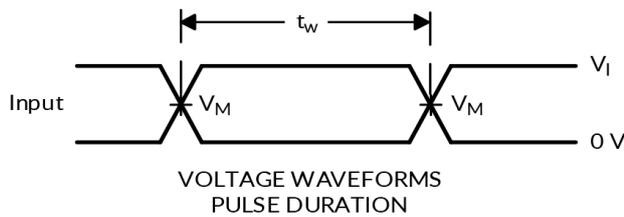
## PARAMETER MEASUREMENT INFORMATION

### Open-Drain



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V$
	$V_i$	$t_r/t_f$					
$1.8V \pm 0.15V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	1k	0.15V
$2.5V \pm 0.2V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	500	0.15V
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	6V	50pF	500	0.3V
$5V \pm 0.5V$	$V_{CC}$	$\leq 2.5ns$	$V_{CC}/2$	$2 \times V_{CC}$	50pF	500	0.3V



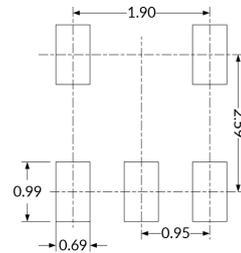
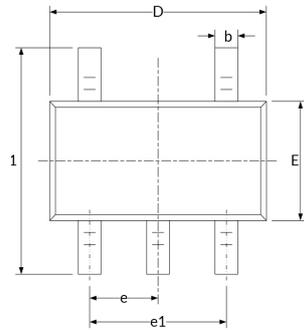


- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.  
Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_0 = 50 \Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

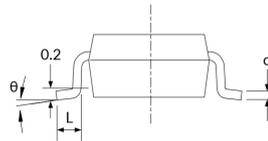
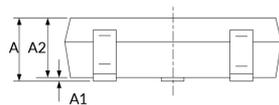
**Figure 1. Load Circuit and Voltage Waveforms**



PACKAGE OUTLINE DIMENSIONS  
SOT23-5<sup>(3)</sup>



RECOMMENDED LAND PATTERN (Unit: mm)



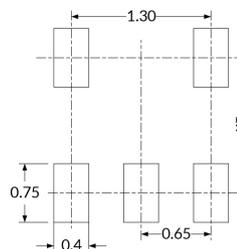
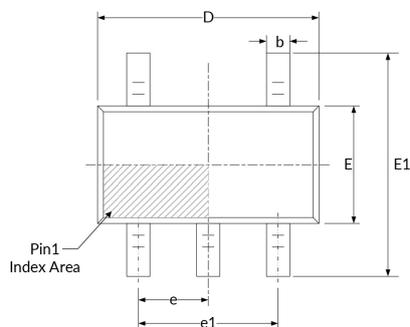
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A <sup>(1)</sup>	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D <sup>(1)</sup>	2.820	3.020	0.111	0.119
E <sup>(1)</sup>	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) <sup>(2)</sup>		0.037(BSC) <sup>(2)</sup>	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
	0°	8°	0°	8°

NOTE:

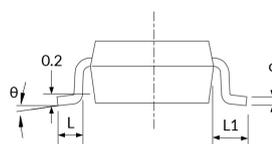
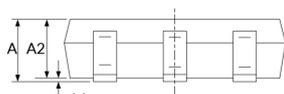
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.



SC70-5<sup>(3)</sup>



RECOMMENDED LAND PATTERN (Unit: mm)



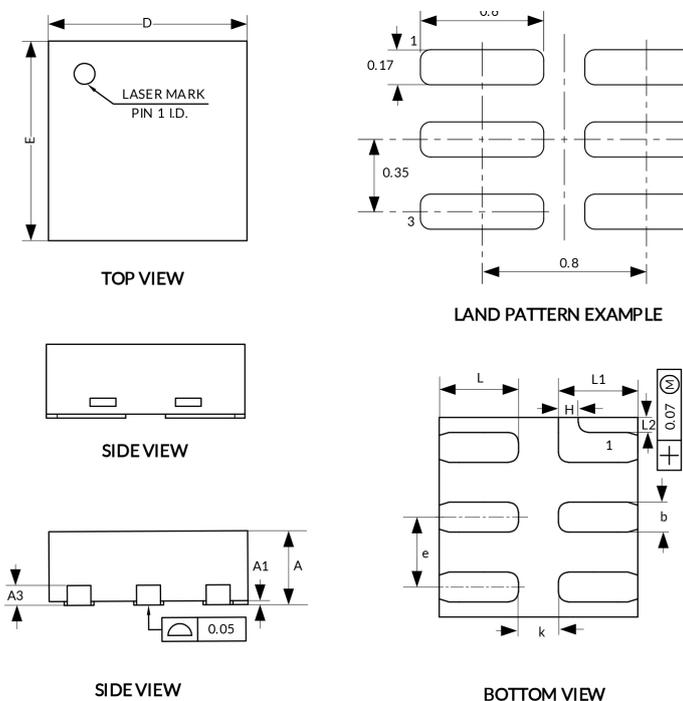
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A <sup>(1)</sup>	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.175	0.003	0.006
D <sup>(1)</sup>	2.000	2.200	0.079	0.087
E <sup>(1)</sup>	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650(BSC) <sup>(2)</sup>		0.026(BSC) <sup>(2)</sup>	
e1	1.300(BSC) <sup>(2)</sup>		0.051(BSC) <sup>(2)</sup>	
L	0.260	0.460	0.010	0.018
L1	0.525		0.021	
	0°	8°	0°	8°

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.



XDFN1X1-6<sup>(3)</sup>



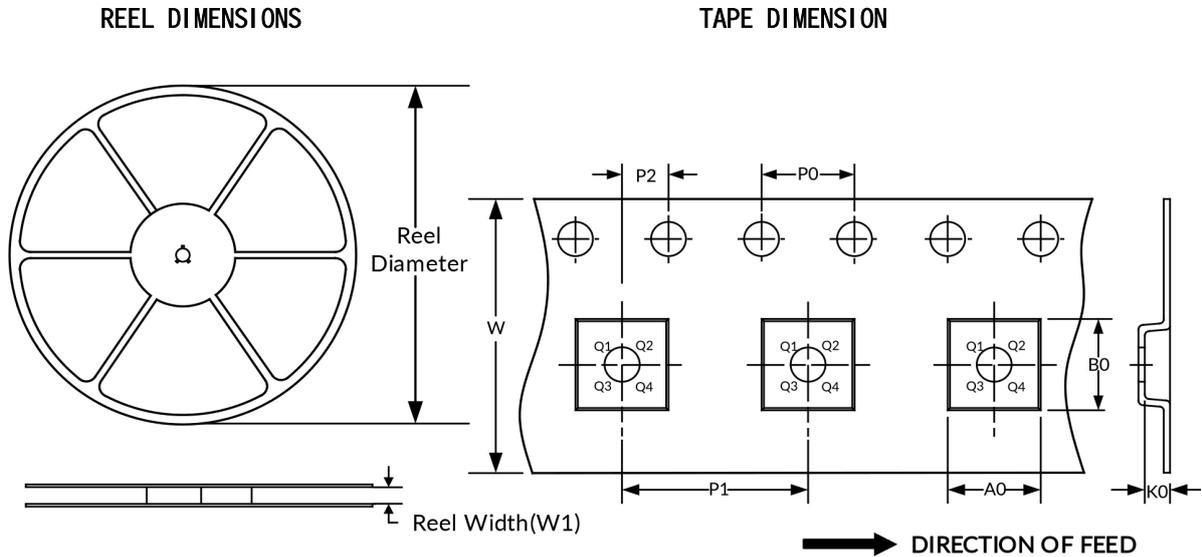
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A <sup>(1)</sup>	0.340	0.400	0.013	0.016
A1	0.000	0.050	0.000	0.002
A3	0.100(REF) <sup>(2)</sup>		0.004(REF) <sup>(2)</sup>	
b	0.100	0.200	0.004	0.008
D <sup>(1)</sup>	0.950	1.050	0.037	0.041
E <sup>(1)</sup>	0.950	1.050	0.037	0.041
e	0.300	0.400	0.012	0.016
H	0.100(REF) <sup>(2)</sup>		0.004(REF) <sup>(2)</sup>	
K	0.150		0.006	
L	0.350	0.450	0.014	0.018
L1	0.350	0.450	0.014	0.018
L2	0.075(REF) <sup>(2)</sup>		0.003(REF) <sup>(2)</sup>	

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. REF is the abbreviation for Reference.
3. This drawing is subject to change without notice.



TAPE AND REEL INFORMATION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SC70-5	7''	9.5	2.25	2.55	1.20	4.0	4.0	2.0	8.0	Q3
SOT23-5	7''	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
XDFN1X1-6	7''	9.5	1.14	1.17	0.56	4.0	4.0	2.0	8.0	Q3

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.